

9/14 2835

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re the Application of:

Fung Leng Chen, et al.

Serial No.: 09/115,444

Filed: 07/14/98

For: High Density Internal Ball Grid Array Integrated Circuit Package

Docket No.: TIS-25912

Examiner: Not Assigned

Art Unit: 2835 #5 / IDS

E. Willis

6-9-99

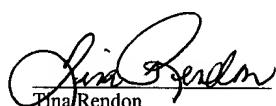
INFORMATION DISCLOSURE STATEMENT

Assistant Commission for Patents

Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner of Patents, Washington, D.C. 20231.



Pina Rendon

11-13-98

Date

Applicants wish to bring the references noted on the enclosed PTO-1449 to the attention of the Patent and Trademark Office. The enclosed articles and/or patents listed on the attached PTO 1449 form are deemed relevant to the above-referenced application.

Please charge any additional fees to deposit account 20-0668.

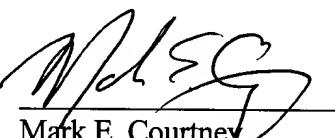
Respectfully submitted,

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